

Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1. (Currently amended) A circuit device comprising:
 a conductive pattern; a circuit element, affixed onto the conductive pattern[[s]]; and an insulating resin, sealing the conductive pattern and the circuit element while exposing at least [[the]] a bottom surface of the conductive pattern;
 wherein recessed areas are in side surfaces of the insulating resin such that outwardly facing outer peripheral parts of the conductive pattern are exposed from within the recessed areas.
 ~~wherein recessed part is formed at the side surface of the insulating resin, and side surface of the conductive pattern that is disposed at peripheral parts is exposed from the recessed part.~~
2. (Original) The device of Claim 1, wherein the circuit device is mounted by attaching brazing material to the exposed side surface and bottom surface of the conductive pattern.
3. (Original) The device of Claim 1, wherein the circuit element is semiconductor element and the conductive pattern that is disposed at the peripheral part and the semiconductor element is connected electrically.
4. (Original) The device of Claim 1, wherein the conductive pattern comprise die pad and bonding pad and circuit element is mounted on the die pad and the bonding pad is disposed so as to surround the die pad.

5. (Original) The device of Claim 1, wherein a plating layer is formed on the rear surface and side surface of the conductive patterns that is exposed from the insulating resin.

6. (Original) The device of Claim 1, wherein a covering resin is formed on the surface of the conductive pattern and the circuit element and the conductive pattern are electrically connected via opening provided in the covering resin.

7. (Original) The device of Claim 6, wherein the covering resin comprises a photosensitive resin.

8. (Withdrawn) A circuit device manufacturing method comprising:
preparing a conductive foil and forming separation grooves that are shallower than the thickness of the conductive foil at least at region of the conductive foil except region to be conductive pattern that form a plurality of mounting portions for circuit elements;
affixing the circuit element onto the respective mounting portions of the conductive pattern;
performing molding with an insulating resin so as to cover the circuit element at the respective mounting portions in a batch and fill the separation groove;
removing the back surface of the conductive foil until the insulating resin is exposed;
removing the conductive patterns at locations corresponding to boundary of the respective mounting portions to form grooves and thereby expose side surface of the conductive patterns; and
performing separation by dicing the insulating resin along the boundary.

9. (Withdrawn) The method of Claim 8, wherein the conductive patterns are electrically connected by plating film formed on the surfaces of the conductive patterns and a plating layer is formed by electrolytic plating on surfaces of the conductive patterns that are exposed from the insulating resin.

10. (Withdrawn) The method of Claim 8, wherein the conductive pattern comprise die pad and bonding pad and circuit element is mounted on the die pad and the bonding pad is disposed so as to surround the die pad.

11. (Withdrawn) The method of Claim 8, wherein the circuit device is mounted by attaching brazing material to the bottom surface and side surface of the conductive pattern that is exposed from the insulating resin.

12. (Withdrawn) The method of Claim 8, wherein the groove is formed to be greater in width than the width of the dicing blade for performing the dicing so that the side surface of the conductive patterns that are exposed from the insulating resin form recessed parts.

13. (Withdrawn) The method of Claim 8, wherein the grooves are formed by etching.

14. (Withdrawn) A circuit device manufacturing method comprising:

preparing a conductive foil;

forming separation groove that is shallower than the thickness of the conductive foil at least at region of the conductive foil except region to be conductive patterns that form a plurality of mounting portions for circuit elements;

affixing the circuit element onto the respective mounting portions of the conductive pattern;

performing molding with an insulating resin so as to cover the circuit element at the respective mounting portions in a batch and fill the separation grooves;

removing the remaining thickness part of the separation grooves to electrically separate the conductive patterns and removing the conductive foil at locations corresponding to boundary of the respective mounting portions to form grooves and thereby expose side surface of the conductive pattern; and

performing separation by dicing the insulating resin along the boundary.

15. (Withdrawn) The method of Claim 14, wherein the conductive pattern comprise die pad and bonding pad and circuit element is mounted on the die pad and the bonding pad is disposed so as to surround the die pad.

16. (Withdrawn) The method of Claim 14, wherein the circuit device is mounted by attaching brazing material to the bottom surface and side surface of the conductive pattern that are exposed from the insulating resin.

17. (Withdrawn) The method of Claim 14, wherein the groove are formed to be greater in width than the width of the dicing blade for performing the dicing so that the side surface of the conductive pattern that is exposed from the insulating resin form recessed part.

18. (Withdrawn) The method of Claim 14, wherein the grooves are formed by etching.